

# GP1S092HCPIF

SMT, Gap : 2mm, Slit : 0.3mm  
Phototransistor Output,  
Compact Transmissive  
Photointerrupter



## ■ Description

**GP1S092HCPIF** is a compact-package, phototransistor output, transmissive photointerrupter, with opposing emitter and detector in a molding that provides non-contact sensing. The compact package series is a result of unique technology combining transfer and injection molding.

This surface mount device has a shaped positioning pin to assure accurate PCB placement, of the emitter and detector. It is unique, because it is one of the few photointerrupters that comes in Tape and Reel packaging, for use with highly automated pick and place equipment.

## ■ Features

1. Transmissive with phototransistor output
2. Highlights:
  - Compact Size
  - Positioning Pin "D" shaped to prevent misalignment
  - Surface Mount Type (SMT)
  - Tape and Reel (T&R) 2 000 pcs per reel
3. Key Parameters:
  - Gap Width : 2mm
  - Slit Width (detector side): 0.3mm
  - Package : 4.5×2.6×2.9 mm
4. RoHS directive compliant

## ■ Agency approvals/Compliance

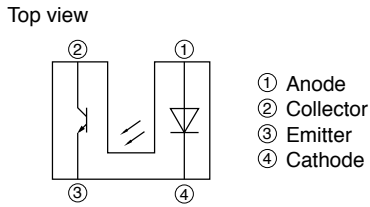
1. Compliant with RoHS directive

## ■ Applications

1. General purpose detection of object presence or motion.
2. Example: printer, lens control for camera

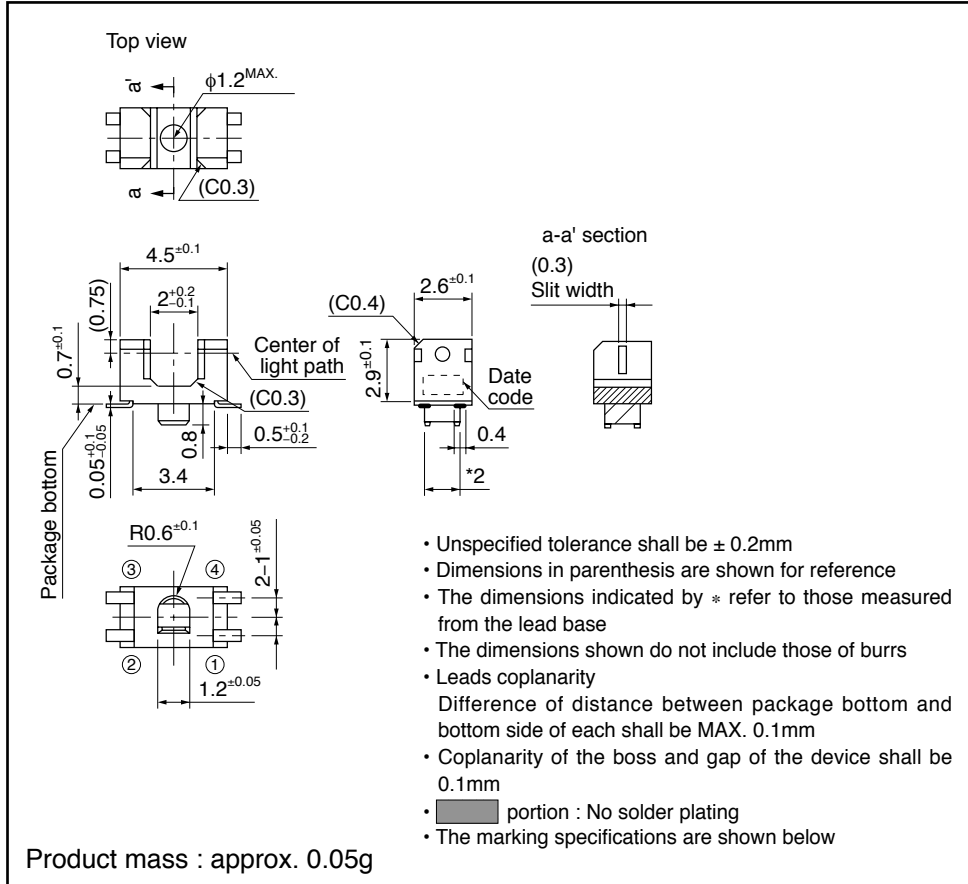
Notice The content of data sheet is subject to change without prior notice.  
In the absence of confirmation by device specification sheets, SHARP takes no responsibility for any defects that may occur in equipment using any SHARP devices shown in catalogs, data books, etc. Contact SHARP in order to obtain the latest device specification sheets before using any SHARP device.

## Internal Connection Diagram



## Outline Dimensions

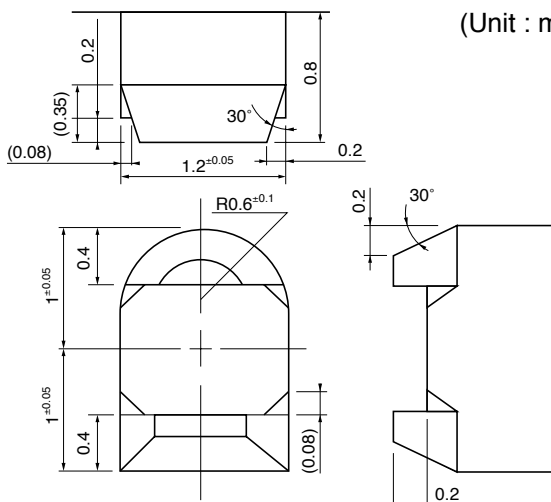
(Unit : mm)



Plating material : SnCu (Cu : TYP. 2%)

## Details of positioning pin dimensions

(Unit : mm)



**Date code (2 digit)**

| 1st digit          |      | 2nd digit           |      |
|--------------------|------|---------------------|------|
| Year of production |      | Month of production |      |
| A.D.               | Mark | Month               | Mark |
| 2000               | 0    | 1                   | 1    |
| 2001               | 1    | 2                   | 2    |
| 2002               | 2    | 3                   | 3    |
| 2003               | 3    | 4                   | 4    |
| 2004               | 4    | 5                   | 5    |
| 2005               | 5    | 6                   | 6    |
| 2006               | 6    | 7                   | 7    |
| 2007               | 7    | 8                   | 8    |
| 2008               | 8    | 9                   | 9    |
| 2009               | 9    | 10                  | X    |
| 2010               | 0    | 11                  | Y    |
| :                  | :    | 12                  | Z    |

repeats in a 10 year cycle

**Rank mark**

There is no rank indicator.

**Country of origin**

Japan

## ■ Absolute Maximum Ratings (T<sub>a</sub>=25°C)

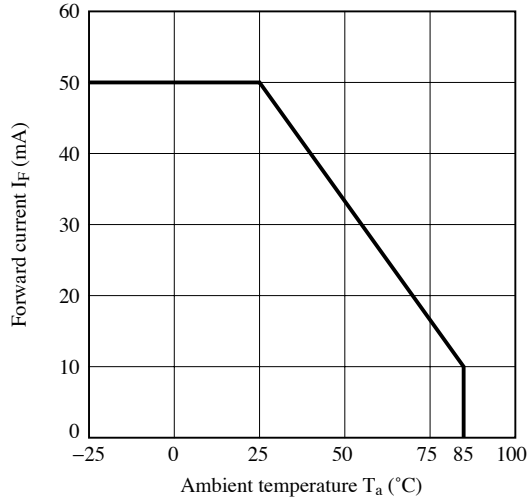
| Parameter                |                             | Symbol           | Rating      | Unit |
|--------------------------|-----------------------------|------------------|-------------|------|
| Input                    | Forward current             | I <sub>F</sub>   | 50          | mA   |
|                          | Reverse voltage             | V <sub>R</sub>   | 6           | V    |
|                          | Power dissipation           | P                | 75          | mW   |
| Output                   | Collector-emitter voltage   | V <sub>CEO</sub> | 35          | V    |
|                          | Emitter-collector voltage   | V <sub>ECO</sub> | 6           | V    |
|                          | Collector current           | I <sub>C</sub>   | 20          | mA   |
|                          | Collector power dissipation | P <sub>C</sub>   | 75          | mW   |
| Total power dissipation  |                             | P <sub>tot</sub> | 100         | mW   |
| Operating temperature    |                             | T <sub>opr</sub> | -25 to +85  | °C   |
| Storage temperature      |                             | T <sub>stg</sub> | -40 to +100 | °C   |
| *1 Soldering temperature |                             | T <sub>sol</sub> | 260         | °C   |

\*1 For 5s or less

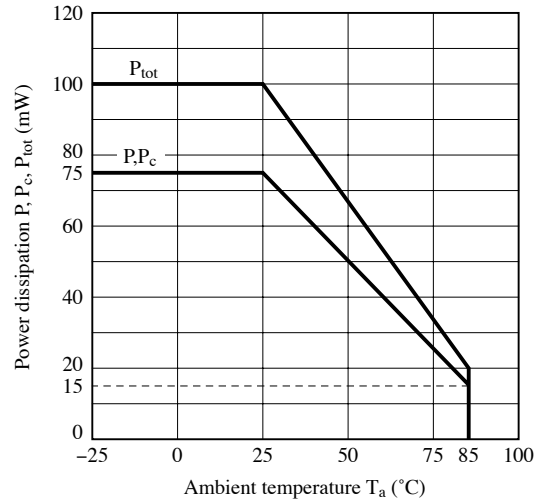
## ■ Electro-optical Characteristics (T<sub>a</sub>=25°C)

| Parameter                |                                      | Symbol               | Condition                                  | MIN.  | TYP. | MAX. | Unit |    |
|--------------------------|--------------------------------------|----------------------|--|---|------|------|------|----|
| Input                    | Forward voltage                      | V <sub>F</sub>       | I <sub>F</sub> =20mA                       | -   | 1.2  | 1.4  | V    |    |
|                          | Reverse current                      | I <sub>R</sub>       | V <sub>R</sub> =3V                         | -   | -    | 10   | μA   |    |
| Output                   | Collector dark current               | I <sub>CEO</sub>     | V <sub>CE</sub> =20V                       | -   | -    | 100  | nA   |    |
| Transfer characteristics | Collector current                    | I <sub>C</sub>       | V <sub>CE</sub> =5V, I <sub>F</sub> =5mA   | 100   | -    | 400  | μA   |    |
|                          | Collector-emitter saturation voltage | V <sub>CE(sat)</sub> | I <sub>F</sub> =10mA, I <sub>C</sub> =40μA | -   | -    | 0.4  | V    |    |
|                          | Response time                        | Rise time            | t <sub>r</sub>                             | V <sub>CE</sub> =5V, I <sub>C</sub> =100μA, R <sub>L</sub> =1kΩ | -    | 50   | 150  | μs |
|                          |                                      | Fall time            | t <sub>f</sub>                             |   | -    | 50   | 150  | μs |

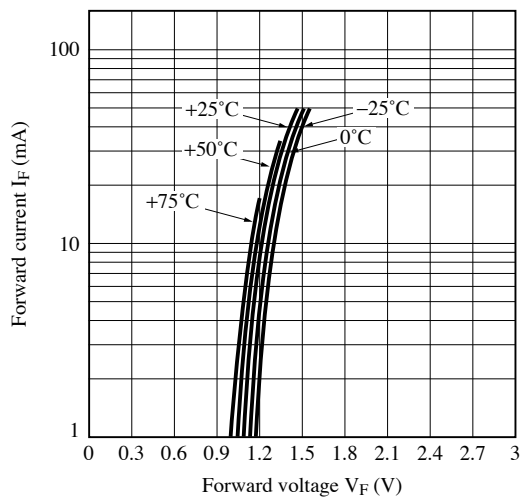
**Fig.1 Forward Current vs. Ambient Temperature**



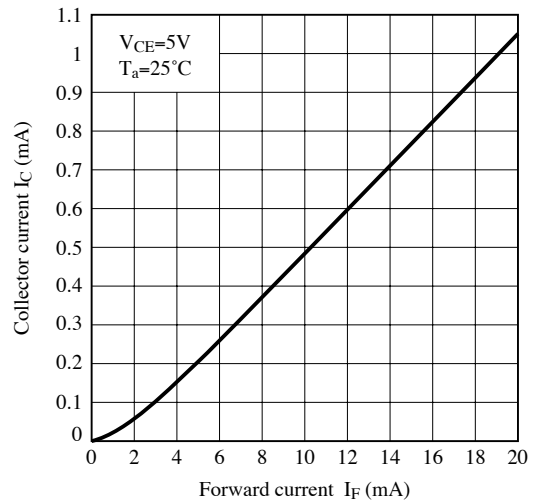
**Fig.2 Power Dissipation vs. Ambient Temperature**



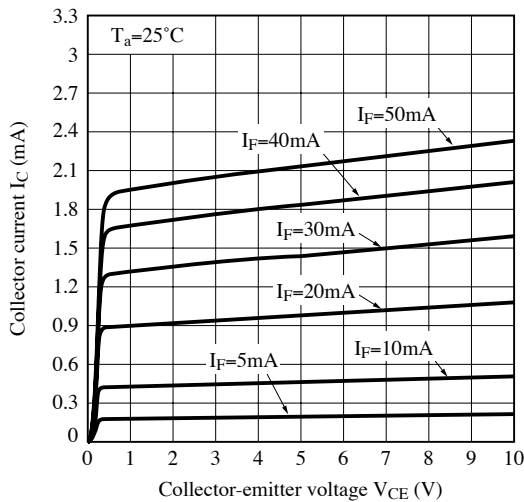
**Fig.3 Forward Current vs. Forward Voltage**



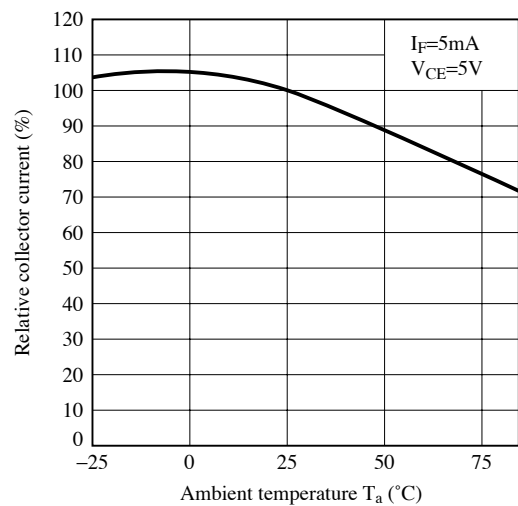
**Fig.4 Collector Current vs. Forward Current**



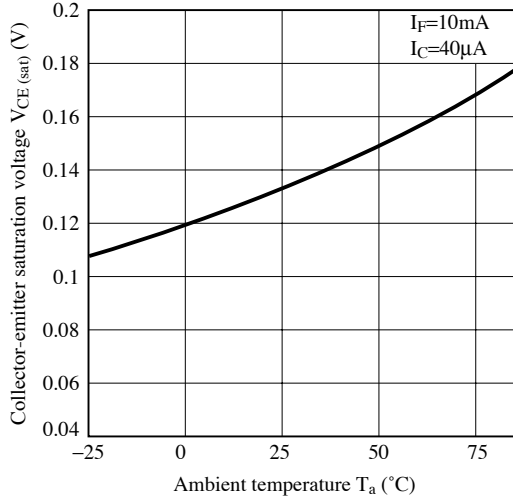
**Fig.5 Collector Current vs. Collector-emitter Voltage**



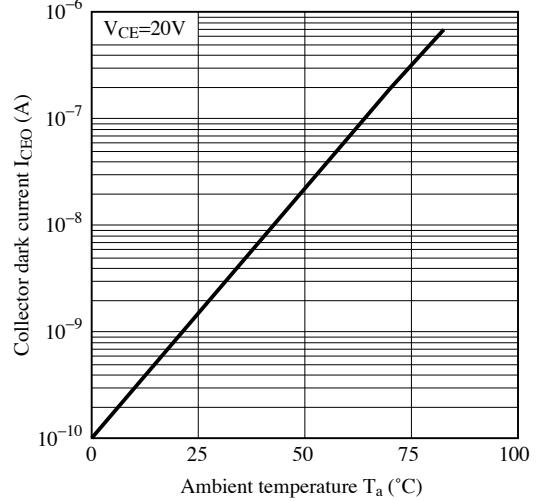
**Fig.6 Relative Collector Current vs. Ambient Temperature**



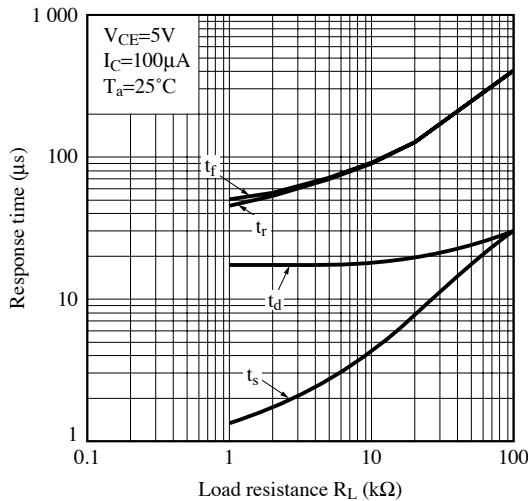
**Fig.7 Collector-emitter Saturation Voltage vs. Ambient Temperature**



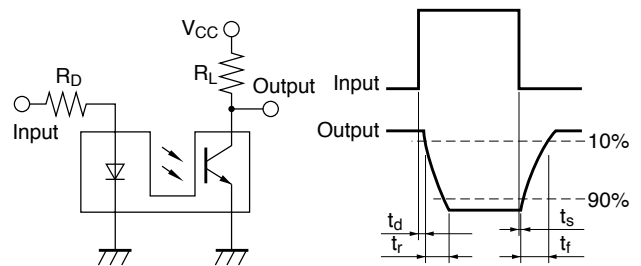
**Fig.8 Collector Dark Current vs. Ambient Temperature**



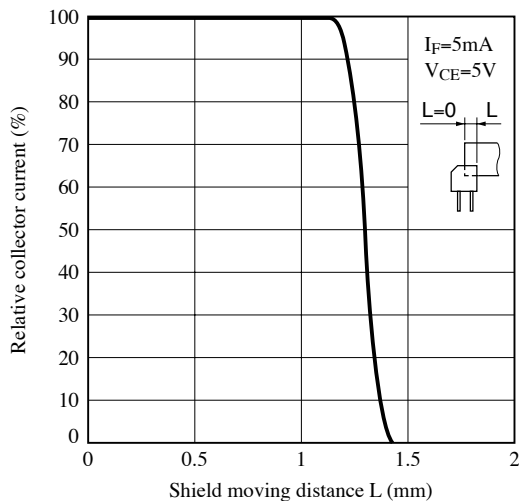
**Fig.9 Response Time vs. Load Resistance**



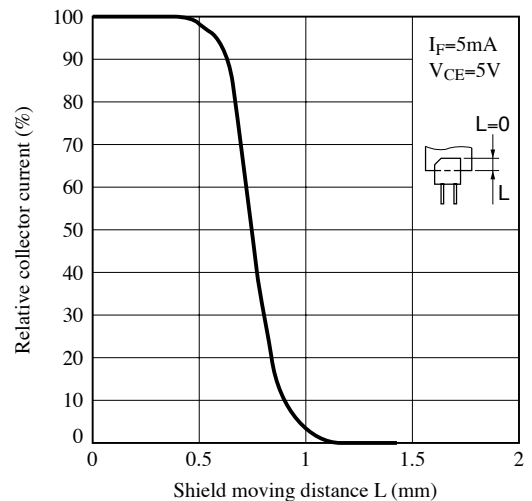
**Fig.10 Test Circuit for Response Time**



**Fig.11 Detecting Position Characteristics (1)**



**Fig.12 Detecting Position Characteristics (2)**



Remarks : Please be aware that all data in the graph are just for reference and not for guarantee.

■ **Design Considerations**

● **Design guide**

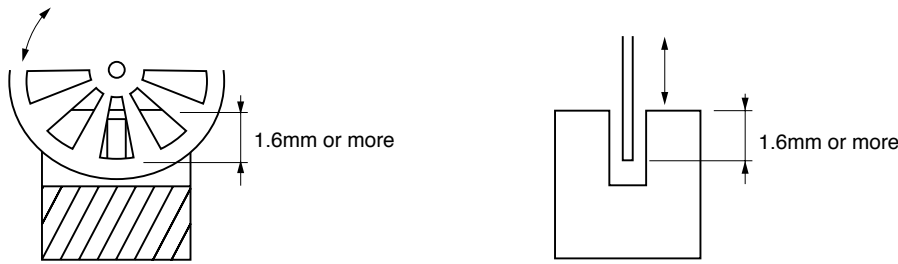
1) Prevention of detection error

To prevent photointerrupter from faulty operation caused by external light, do not set the detecting face to the external light.

2) Position of opaque board

Opaque board shall be installed at place 1.6mm or more from the top of elements.

(Example)



This product is not designed against irradiation and incorporates non-coherent IRED.

● **Degradation**

In general, the emission of the IRED used in photointerrupter will degrade over time.

In the case of long term operation, please take the general IRED degradation (50% degradation over 5 years) into the design consideration.

● **Used parts**

This product is assembled using the below parts.

• Photodetector (qty. : 1)

| Category        | Material     | Maximum Sensitivity wavelength (nm) | Sensitivity wavelength (nm) | Response time (μs) |
|-----------------|--------------|-------------------------------------|-----------------------------|--------------------|
| Phototransistor | Silicon (Si) | 930                                 | 700 to 1 200                | 20                 |

• Photo emitter (qty. : 1)

| Category                               | Material                | Maximum light emitting wavelength (nm) | I/O Frequency (MHz) |
|--|-------------------------|--|---------------------|
| Infrared emitting diode (non-coherent) | Gallium arsenide (GaAs) | 950                                    | 0.3                 |

• Material

| Case  | Lead frame | Lead frame plating |
|---|------------|--------------------|
| Black polyphernylene sulfide resin (UL94 V-0) | 42Alloy    | SnCu plating       |

---

**■ Manufacturing Guidelines****● Storage and management after open****Storage condition**

Storage temp.: 5 to 30°C, Storage humidity : 70%RH or less at regular packaging.

**Treatment after opening the moisture-proof package**

After opening, you should mount the products while keeping them on the condition of 5 to 25°C and 70%RH or less in humidity within 4 days.

After opening the bag once even if the prolonged storage is necessary, you should mount the products within two weeks.

And when you store the rest of products you should put into a DRY BOX. Otherwise after the rest of products and silicagel are sealed up again, you should keep them under the condition of 5 to 30°C and 70%RH or less in humidity.

**Baking before mounting**

When the above-mentioned storage method could not be executed, please process the baking treatment before mounting the products.

However the baking treatment is permitted within one time.

Recommended condition : 125°C, 16 to 24 hours

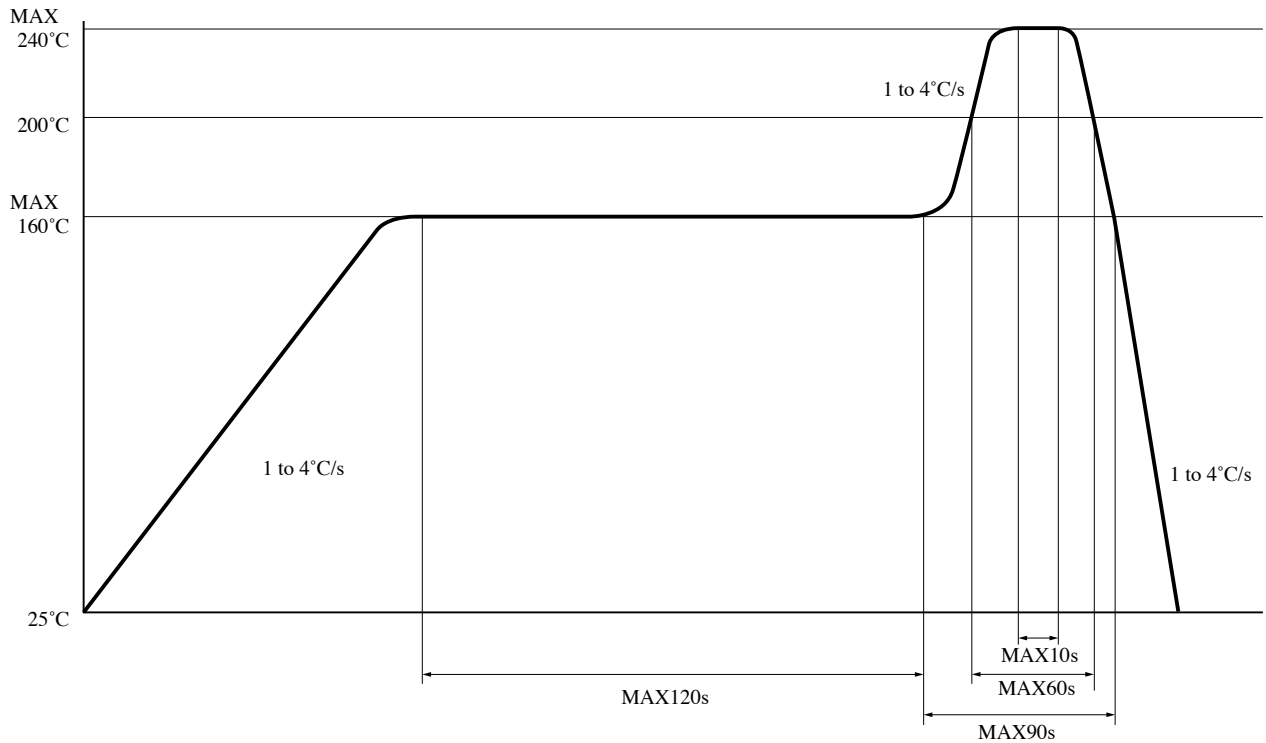
\*Do not process the baking treatment with the product wrapped. When the baking treatment processing, you should move the products to a metallic tray or fix temporarily the products to substrate.



● **Soldering Method**

**Reflow Soldering:**

Reflow soldering should follow the temperature profile shown below.  
 Soldering should not exceed the curve of temperature profile and time.  
 Please solder within one time.



**Hand soldering**

Hand soldering should be completed within 3 s when the point of solder iron is below 350°C.  
 Please solder within one time.  
 Please don't touch the terminals directly by soldering iron.  
 Soldered product shall treat at normal temperature.

**Other notice**

Please take care not to let any external force exert on lead pins.  
 Please test the soldering method in actual condition and make sure the soldering works fine, since the impact on the junction between the device and PCB varies depending on the cooling and soldering conditions.

**Lead terminals**

Lead terminals of this product are tin copper alloy plated. Before usage, please evaluate solderability with actual conditions and confirm. And the uniformity in color for the lead terminals are not specified.

---

**● Cleaning instructions****Solvent cleaning :**

Solvent temperature should be 45°C or below. Immersion time should be 3 minutes or less.

**Ultrasonic cleaning :**

Do not execute ultrasonic cleaning.

**Recommended solvent materials :**

Ethyl alcohol, Methyl alcohol and Isopropyl alcohol.

**● Presence of ODC**

This product shall not contain the following materials.

And they are not used in the production process for this product.

Regulation substances : CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform)

Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.

This product shall not contain the following materials banned in the RoHS Directive (2002/95/EC).

•Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBB), Polybrominated diphenyl ethers (PBDE).

**Package specification**

**Package materials**

Carrier tape : PS (with anti-static material)

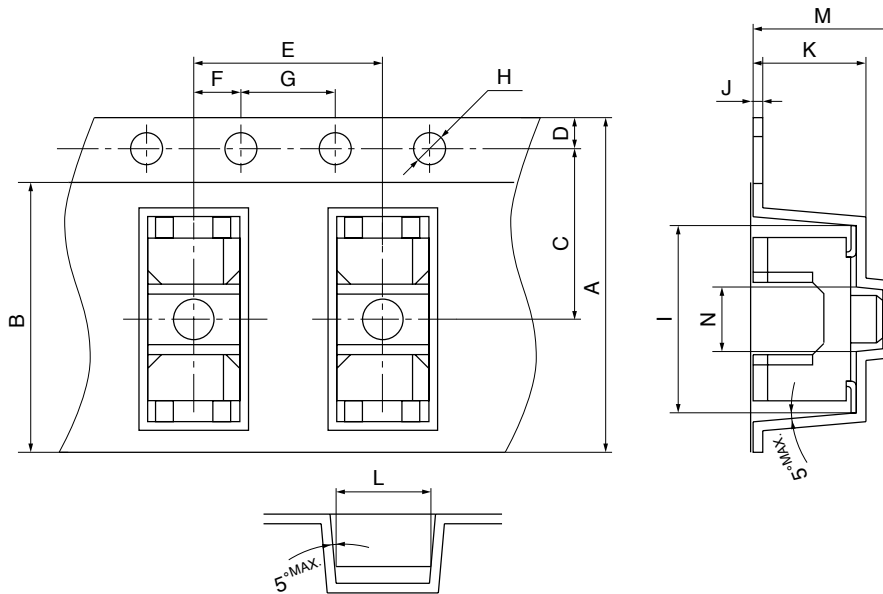
Cover tape : PET (three layer system)

Reel : PS

**Package method**

2 000 pcs of products shall be packaged in a reel. One reel with silicagel is enclosed in aluminum laminated bag. After sealing up the bag, it enclosed in one case (5 bags/case).

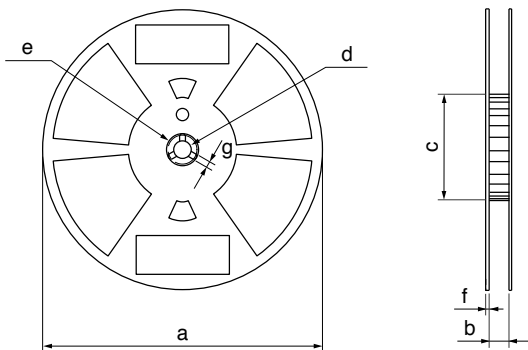
**Carrier tape structure and Dimensions**



Dimensions List (Unit : mm)

| A                                  | B                                   | C        | D        | E       | F       | G        |
|------------------------------------|-------------------------------------|----------|----------|---------|---------|----------|
| 12±0.3                             | 9.5 <sup>+0.3</sup> <sub>-0.2</sub> | 5.5±0.05 | 1.75±0.1 | 8±0.1   | 2±0.05  | 4±0.1    |
| H                                  | I                                   | J        | K        | L       | M       | N        |
| φ1.5 <sup>+0.1</sup> <sub>-0</sub> | 6.1±0.1                             | 0.4±0.05 | 3.2±0.1  | 2.8±0.1 | 4.3±0.1 | 1.45±0.1 |

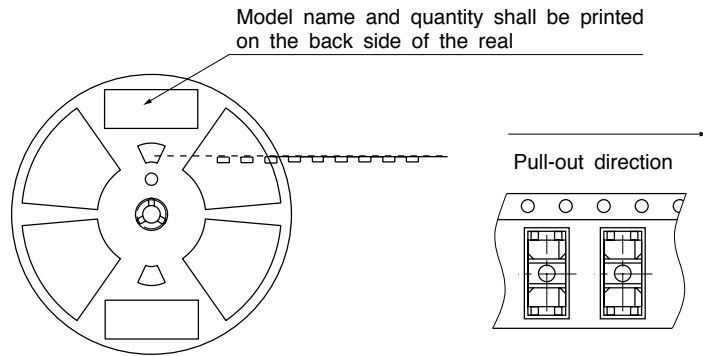
**Reel structure and Dimensions**



Dimensions List (Unit : mm)

| a     | b     | c     | d      |
|-------|-------|-------|--------|
| 330±1 | 13±1  | 80±1  | 13±0.5 |
| e     | f     | g     |        |
| 21±1  | 2±0.5 | 2±0.5 |        |

## Direction of product insertion



[Packing : 2 000pcs/reel]

## Storage method

Storage conditions should follow the condition shown below.

Storage temperature : 5 to 30°C

Storage humidity : 70%RH or less

**■ Important Notices**

· The circuit application examples in this publication are provided to explain representative applications of SHARP devices and are not intended to guarantee any circuit design or license any intellectual property rights. SHARP takes no responsibility for any problems related to any intellectual property right of a third party resulting from the use of SHARP's devices.

· Contact SHARP in order to obtain the latest device specification sheets before using any SHARP device. SHARP reserves the right to make changes in the specifications, characteristics, data, materials, structure, and other contents described herein at any time without notice in order to improve design or reliability. Manufacturing locations are also subject to change without notice.

· Observe the following points when using any devices in this publication. SHARP takes no responsibility for damage caused by improper use of the devices which does not meet the conditions and absolute maximum ratings to be used specified in the relevant specification sheet nor meet the following conditions:

(i) The devices in this publication are designed for use in general electronic equipment designs such as:

- Personal computers
- Office automation equipment
- Telecommunication equipment [terminal]
- Test and measurement equipment
- Industrial control
- Audio visual equipment
- Consumer electronics

(ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection

with equipment that requires higher reliability such as:

- Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
- Traffic signals
- Gas leakage sensor breakers
- Alarm equipment
- Various safety devices, etc.

(iii) SHARP devices shall not be used for or in connection with equipment that requires an extremely high level of reliability and safety such as:

- Space applications
- Telecommunication equipment [trunk lines]
- Nuclear power control equipment
- Medical and other life support equipment (e.g., scuba).

· If the SHARP devices listed in this publication fall within the scope of strategic products described in the Foreign Exchange and Foreign Trade Law of Japan, it is necessary to obtain approval to export such SHARP devices.

· This publication is the proprietary product of SHARP and is copyrighted, with all rights reserved. Under the copyright laws, no part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, for any purpose, in whole or in part, without the express written permission of SHARP. Express written permission is also required before any use of this publication may be made by a third party.

· Contact and consult with a SHARP representative if there are any questions about the contents of this publication.

## X-ON Electronics

Largest Supplier of Electrical and Electronic Components

*Click to view similar products for* [Optical Switches](#), [Transmissive](#), [Phototransistor Output](#) *category:*

*Click to view products by* [Sharp](#) *manufacturer:*

Other Similar products are found below :

[LTH-301-07](#) [LTH-301-23](#) [E3C-X2C](#) [E3S-LS20B4S1](#) [E3SX2CE4](#) [RPI-0125B](#) [RPI-2501](#) [RPI-576A](#) [KRA021](#) [LTH-306-04M](#) [LTH-309-08](#)  
[HOA0865-100](#) [HOA1961-055](#) [E3F-3C4](#) [LTH-306-01](#) [EESX677C1JR01M](#) [SIT506F-A](#) [HOA1883-501](#) [PT928-6B-F](#) [RPI-243](#) [EE-SX675P-](#)  
[WR 1M](#) [OPB806](#) [EE-SX1128](#) [OPB857Z](#) [EE-SV3-B](#) [EE-SJ3-D](#) [RPI-0226](#) [EE-SX672R](#) [EE-SX670P-WR 1M](#) [LTH-301-32](#)  
[EESX674PWR1M](#) [EE-SX952-W 1M](#) [RPI-0352E](#) [RPI-352C40N](#) [DY-ITR002](#) [DY-ITR1100](#) [DY-ITR9909-W2](#) [HOA0825-001](#) [HOA0825-003](#)  
[HOA0860-N51](#) [HOA0861-N55](#) [HOA0861-P55](#) [HOA0861-T55](#) [HOA0866-P55](#) [HOA0866-T55](#) [HOA0867-P55](#) [HOA0867-T55](#) [HOA0870-](#)  
[T51](#) [HOA0871-L55](#) [HOA0872-N55](#)